

AIR COOLING

Series Copper Standard SF

dau

A Miba Group Company



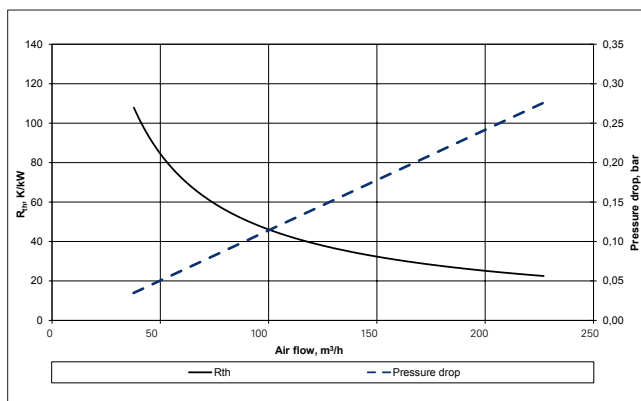
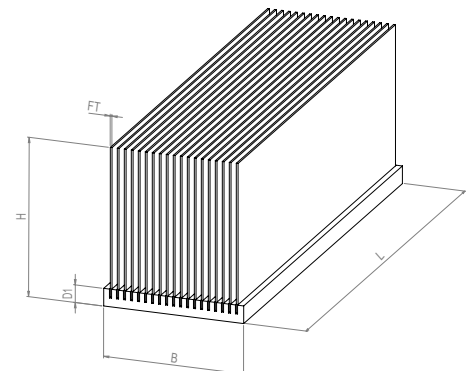
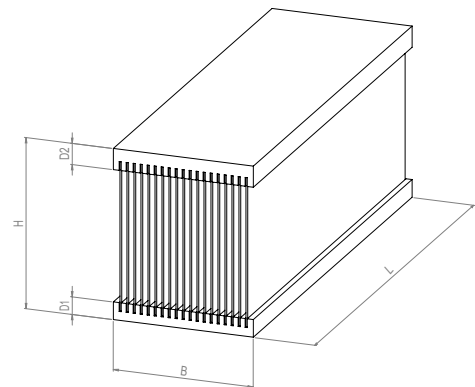
APPLICATION

Customized copper Heat Sinks for efficient air cooling of IGBTs and resistors. DAU offers high performance customized solutions for all IGBT and resistor types available on the market.

GENERAL CHARACTERISTICS

DAU Series SF is used for extremely high power IGBT and resistor applications. The unique solder technique creates an excellent interface between the copper baseplate and the copper fins. Due to the thermal conductivity of copper the efficiency is higher than other aluminium types.

| | Width B mm | Base- plate D1 mm | Thick- ness D2 mm | Fin Thick- ness FT mm | Height H mm | Length L mm |
|------|------------------|----------------------------|----------------------------|-----------------------------------|-------------------|-------------------|
| min. | 40 | 8 | 8 | 0,5 | 25 | 60 |
| max. | 300 | 25 | 15 | 2 | 150 | 400 |



DESCRIPTION

No. of modules: 7
Module size: 68x90 [mm]
Power dissipation: 140 [W/modul]
Thermocouple: Type K
Air inlet temperature: 25[°C]